

SMT ADHESIVE - Heat Cure Type

JU – 41P

■ Features

- Ensures excellent printing with high dot profile.
- High slump resistance.
- Very high bonding strength.
- Long shelf life.

Before curing	Application		Printing
	Composition		Epoxy
	State • Color		Paste • Red
	Specific gravity		1.22 ± 0.05
	Viscosity (Pa.s • 30°C)		100 ± 10
	Thixotropy (30°C)		3.5 ± 0.5
	Non-volatile (105°C • 3 hr)		> 99%
	Viscosity variation rate (105°C, 20 hrs)		5%
	Shelf life	At room temp. (20°C)	
Below 10°C		6 months	
After curing	State • Color		Polymer, dark red
	Bonding strength	2125 square chip	> 3 kg
		Minimold Tr	> 3 kg
	Copper plate corrosion (40°C 90%RH72hr)		Passed
	Heat resistivity (250°C × 10sec.)		Passed
	Surface insulation resistant	Initial value (Ω)	> 1 × 10 ¹²
		40°C, 95%RH × 96hr(Ω)	> 1 × 10 ¹¹
	Water absorption		0.1%
	Dielectric constant (1 MHz)		3.4
Dielectric tangent (1 MHz)		0.016	

- ◆ Curing condition : 120°C × > 90sec.
 130°C ~ 150°C × > 60sec.

KOKI COMPANY LIMITED

32-1, Senju Asahi-cho, Adachi-ku, Tokyo 120

Tel : (03) 5244-1521 Fax : (03) 5244-1527